



N-channel Enhancement-mode Power MOSFET

- Simple Drive Requirement**
- Low On-resistance**
- Fast Switching Performance**
- RoHS-compliant, halogen-free**

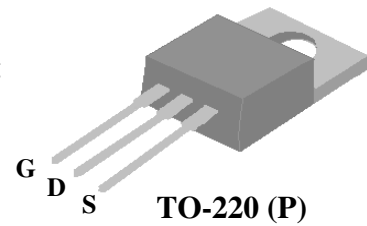


BV_{DSS}	75V
$R_{DS(ON)}$	5mΩ
I_D	125A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The AP95T07BGP-HF-3 is in the TO-220 through-hole package which is used where a low PCB footprint or an attached heatsink is required.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	75	V
V_{GS}	Gate-Source Voltage	±20	V
I_D at $T_C=25^\circ\text{C}$	Continuous Drain Current (Chip)	125	A
I_D at $T_C=25^\circ\text{C}$	Continuous Drain Current ³	100	A
I_D at $T_C=100^\circ\text{C}$	Continuous Drain Current	78	A
I_{DM}	Pulsed Drain Current ¹	400	A
P_D at $T_C=25^\circ\text{C}$	Total Power Dissipation	138.9	W
P_D at $T_A=25^\circ\text{C}$	Total Power Dissipation	2	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	0.9	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient	62	°C/W

Ordering Information

AP95T07BGP-HF-3TB **RoHS-compliant halogen-free TO-220, shipped in tubes (50pcs/tube)**



Electrical Specifications at $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	75	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=60A$	-	-	5	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	4	V
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=60A$	-	90	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V$	-	-	25	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$I_D=40A$	-	96	154	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=60V$	-	25	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	40	-	nC
$t_{d(on)}$	Turn-on Delay Time ²	$V_{DS}=40V$	-	20	-	ns
t_r	Rise Time	$I_D=40A$	-	70	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=1\Omega$	-	37	-	ns
t_f	Fall Time	$V_{GS}=10V$	-	15	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	5100	8160	pF
C_{oss}	Output Capacitance	$V_{DS}=25V$	-	700	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	340	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	1.3	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_S=40A, V_{GS}=0V$	-	-	1.3	V
t_{rr}	Reverse Recovery Time ²	$I_S=10A, V_{GS}=0V$	-	55	-	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=100A/\mu s$	-	110	-	nC

Notes:

1. Pulse width limited by maximum junction temperature.
2. Pulse test
3. Package limitation current is 100A, calculated continuous current based on maximum allowable junction temperature is 125A.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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Typical Electrical Characteristics

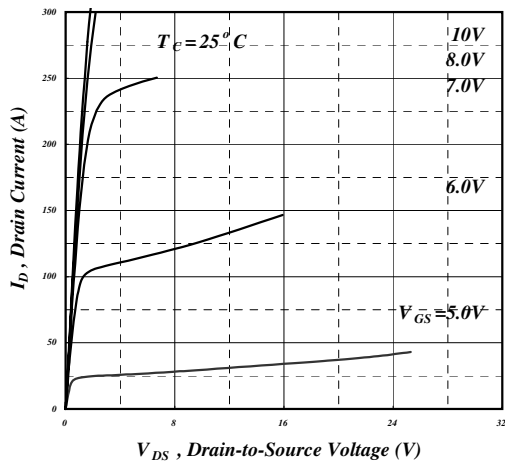


Fig 1. Typical Output Characteristics

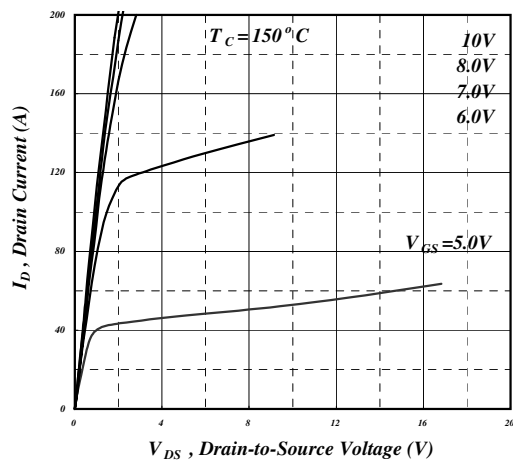


Fig 2. Typical Output Characteristics

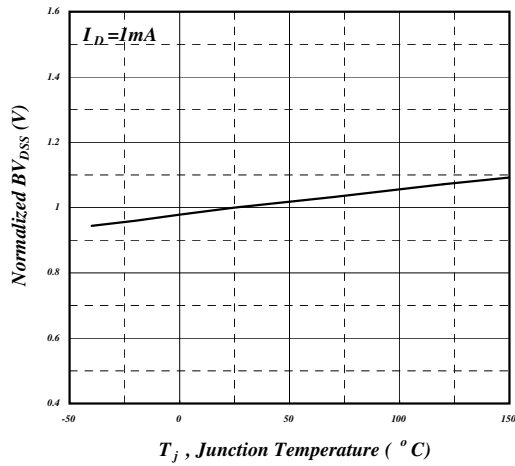


Fig 3. Normalized BV_{DSS} vs. Junction Temperature

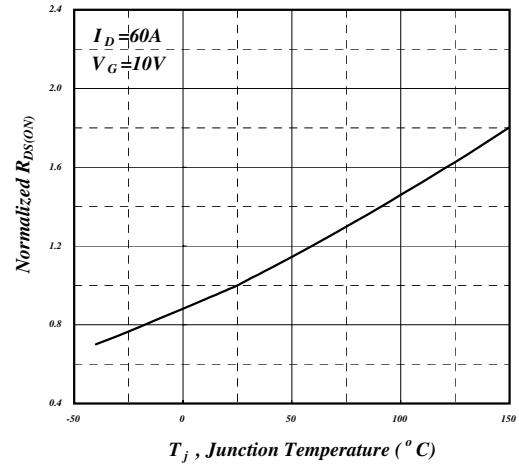


Fig 4. Normalized $R_{DS(on)}$ vs. Junction Temperature

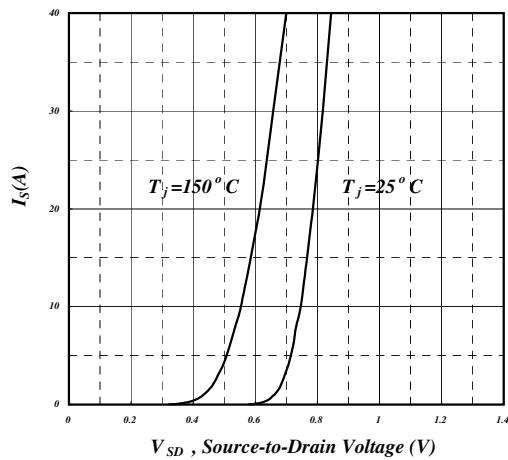


Fig 5. Forward Characteristic of Reverse Diode

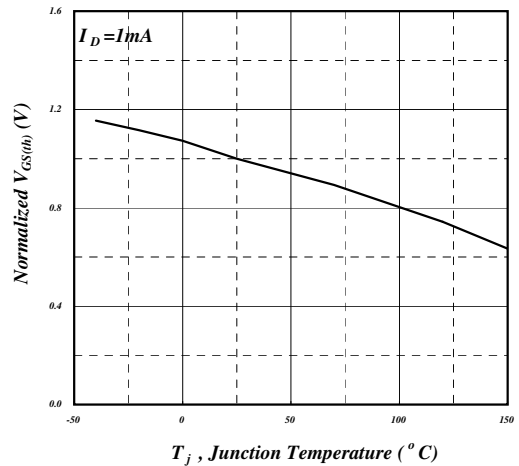


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



Typical Electrical Characteristics (cont.)

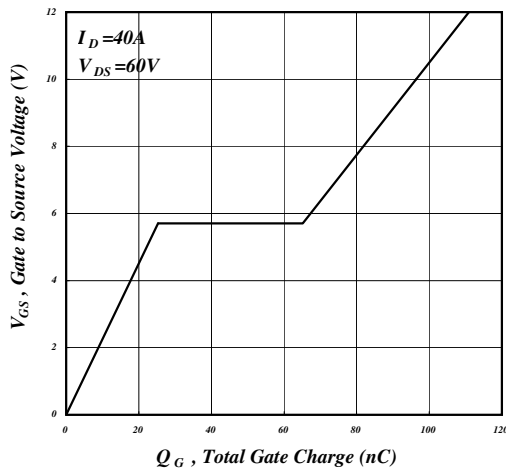


Fig 7. Gate Charge Characteristics

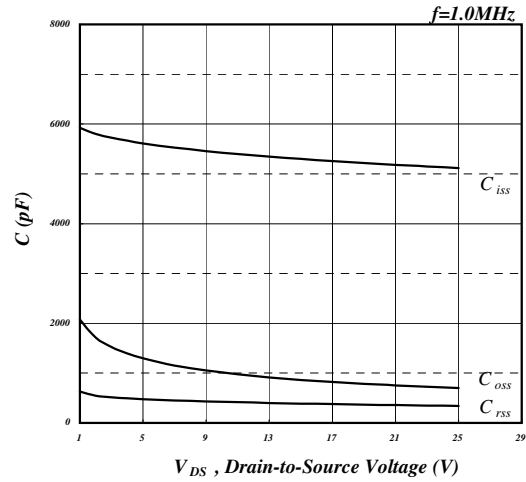


Fig 8. Typical Capacitance Characteristics

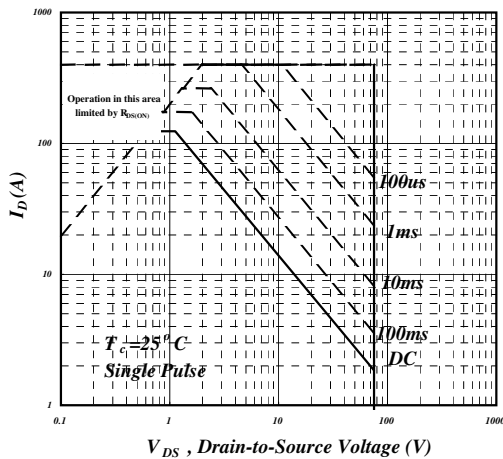


Fig 9. Maximum Safe Operating Area

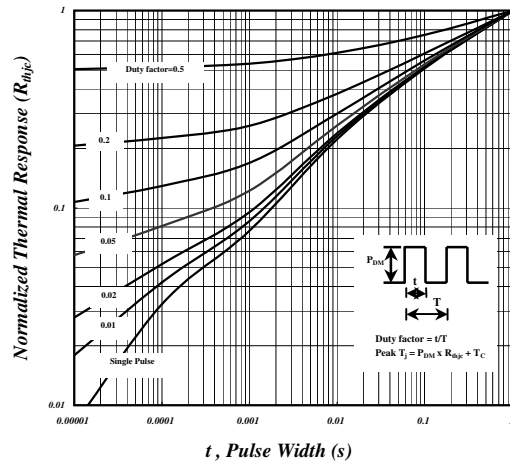


Fig 10. Effective Transient Thermal Impedance

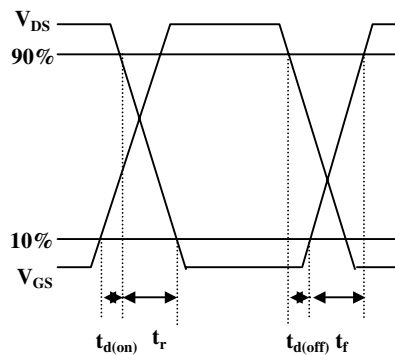


Fig 11. Switching Time Waveform

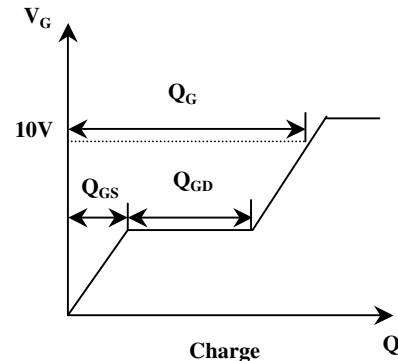
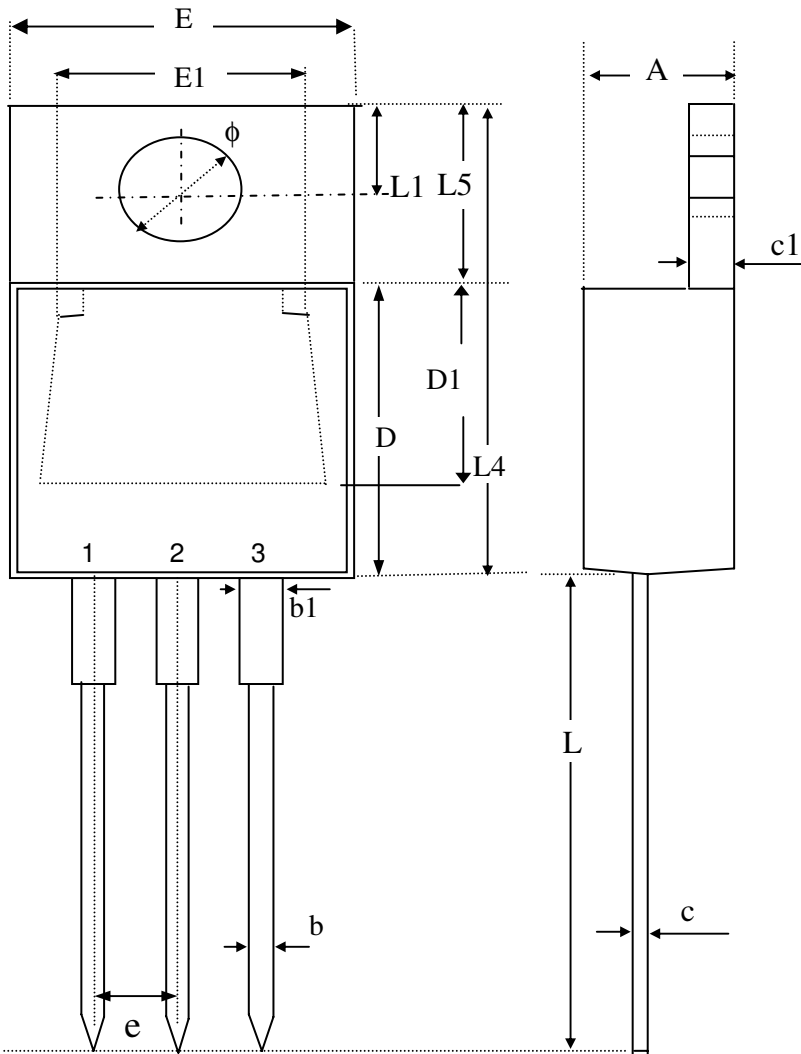


Fig 12. Gate Charge Waveform



Package Dimensions: TO-220



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	4.40	4.60	4.80
b	0.76	0.88	1.00
D	8.60	8.80	9.00
c	0.36	0.43	0.50
E	9.80	10.10	10.40
L4	14.70	15.00	15.30
L5	6.20	6.40	6.60
D1	5.10 REF.		
c1	1.25	1.35	1.45
b1	1.17	1.32	1.47
L	13.25	13.75	14.25
e	2.54 REF.		
L1	2.60	2.75	2.89
ϕ	3.71	3.84	3.96
E1	7.4 REF.		

1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.

Marking Information: TO-220

